

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : TBA
Applicant(s) : Edward G. Combs *et al.*
Filed : March 18, 2004
TC/A.U. : TBA
Examiner : TBA
Docket No. : 36080-00802
Customer No. : 27171
Title : *Method of Manufacturing an Enhanced Thermal Dissipation Integrated Circuit Package* (as amended)

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Prior to examination, please amend the above-referenced application as follows:

Amendments to the Title begin on page 2 of this paper.

Amendments to the Abstract begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks begin on page 8 of this paper.

IN THE TITLE

Please replace the Title with the following:

Method of Manufacturing an Enhanced Thermal Dissipation Integrated Circuit Package